

# SPECIFICATION



REFOND P/N

RF-A3E31-W60E-B1

D` 6

Mass Production

## Contents

### 1. Description

#### 1.1 General Description

#### 1.2 Features

#### 1.3 Application

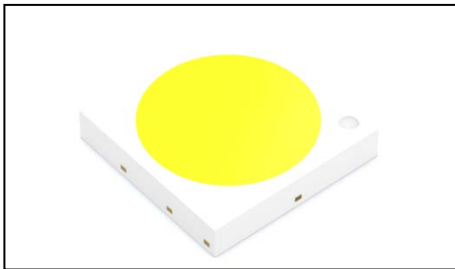
#### 1.4 Package Dimension

#### 1.5 Product Tj 51 Tf ( )Tj -C5-<</MCID 26 >>BDC /TT1 1 Tf -9.eferenc. Tw 12 -0 0 12 36 567.36 T



# 1. Description

## 1.1 General Description



The White LED, which was fabricated by using a blue chip and the phosphor.

Product Package:3.0mmX3.0mmX0.55mm.

>76

3.0mmX3.0mmX0.55mm

## 1.2 Features

EMC Package.7? 5

Extremely wide viewing angle.

Suitable for all SMT assembly and solder process. E? F

Available on tape and reel.

Moisture sensitivity level: Level 2. >VWV\$

RoHS compliant. RoHS

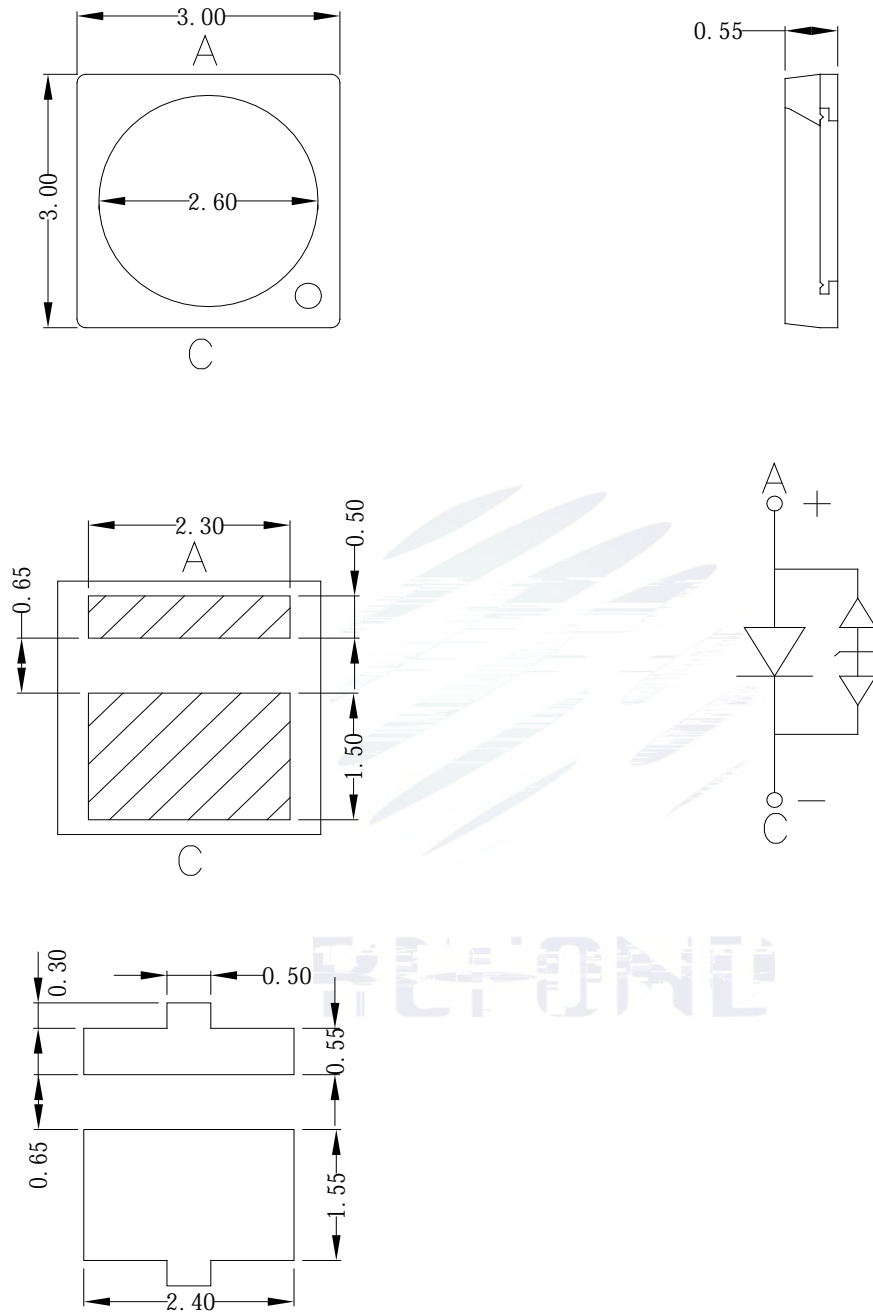
Qualifications: The product qualification test plan is based on the guidelines of AEC-Q102 Stress Test Qualification for Automotive Grade Discrete Semiconductors

375ŽC#" \$

## 1.3 Application

Automotive Lighting Interior and Exterior.

## 1.4 Package Dimension



### Notes

#ž All dimensions units are millimeters.

\$ž All dimensions tolerances are  $\pm 0.2\text{mm}$  unless otherwise noted.

f "ž

## 1.5 Product Parameters

Table 1-1 Electrical / Optical Characteristics at Ts=25°C

Item	Symbol	Test Condition	Value			Unit
			Min.	Typ.	Max.	
Forward Voltage	$V_F$	$I_F=150\text{mA}$	2.8	---	3.4	V
Reverse Current	$I_R$	$V_R=5\text{V}$	---	---	10	$\mu\text{A}$
Luminous Flux		$I_F=150\text{mA}$	50	---	75.3	lm
Viewing Angle		$I_F=150\text{mA}$	---	120	---	deg
Thermal Resistance.	$R_{THJ-S}$	$I_F=150\text{mA}$	---	14	18	/W

Table 1-2 Absolute Maximum Ratings at Ts=25°C

Parameter	Symbol	Rating	Units
Power Dissipation	$P_D$	850	mW
Forward Current	$I_F$	250	mA
Peak Forward Current	$I_{FP}$	350	mA
Reverse Voltage	$V_R$	5	V
Electrostatic Discharge (HBM)	$E_{SD}$	8000	V
Operating Temperature	$T_{OPR}$	-40 ~ +125	
Storage Temperature	$T_{STG}$	-40 ~ +125	
Junction Temperature	$T_J$	150	

## Notes

1. 1/10 Duty cycle, 10ms pulse width.      # " \_ et      #!#" ž
2. The above forward voltage measurement allowance tolerance is  $\pm 0.1V$ .      f " ž#Hž
3. The above color coordinates measurement allowance tolerance is  $\pm 0.005$ .       $\pm$  " ž " " ž
4. T



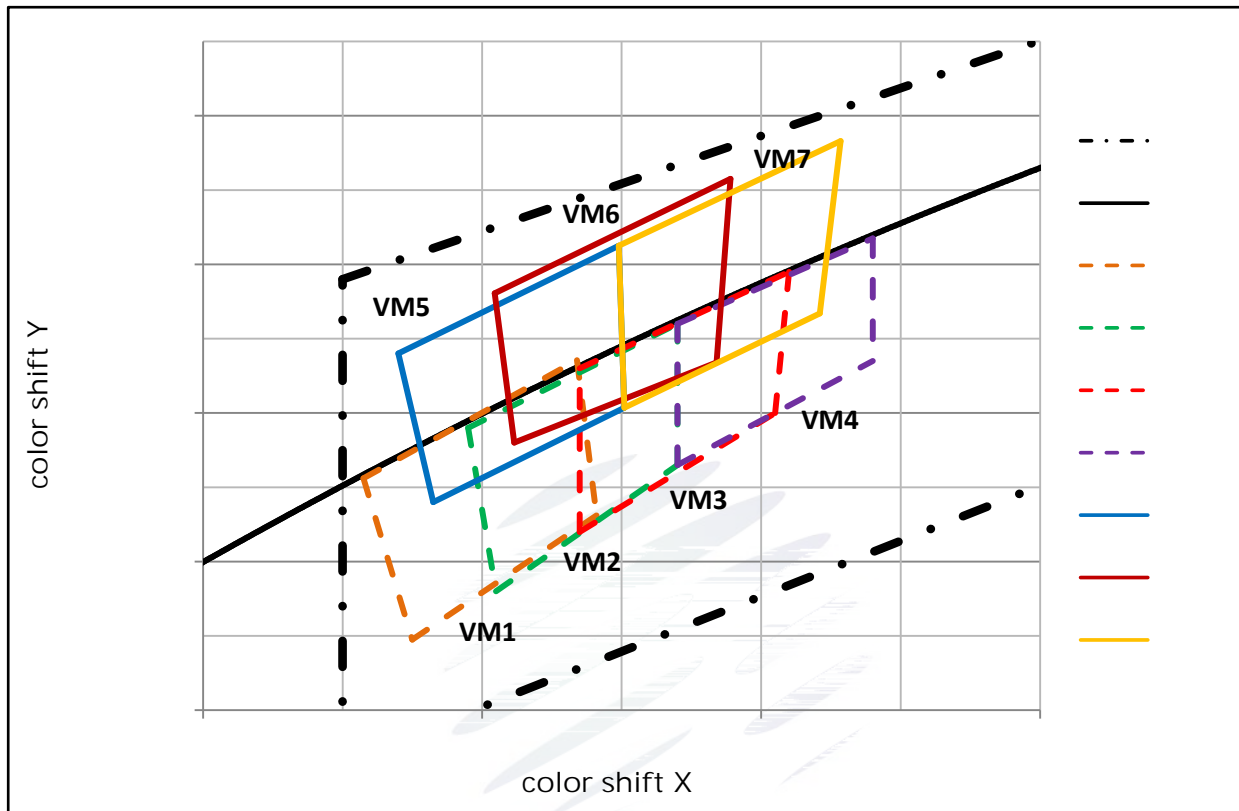


Fig. 1-6 The C.I.E Chromaticity Diagram CIE


 Table 1-4

BIN CODE	CIE-X1	CIE-Y1	CIE-X2	CIE-Y2	CIE-X3	CIE-Y3	CIE-X4	CIE-Y4
VM1	0.3150	0.2995	0.3115	0.3212	0.3268	0.3371	0.3282	0.3162
VM2	0.3210	0.3060	0.3190	0.3280	0.3340	0.3420	0.3340	0.3230
VM3	0.3270	0.3140	0.3270	0.3360	0.3420	0.3490	0.3410	0.3300
VM4	0.3340	0.3230	0.3340	0.3420	0.3480	0.3535	0.3480	0.3370
VM5	0.3165	0.3180	0.3140	0.3380	0.3298	0.3525	0.3302	0.3307
VM6	0.3223	0.3260	0.3209	0.3461	0.3378	0.3615	0.3368	0.3368
VM7	0.3302	0.3307	0.3298	0.3525	0.3457	0.3666	0.3442	0.3434

## 1.7 Typical Optical Characteristics Curves

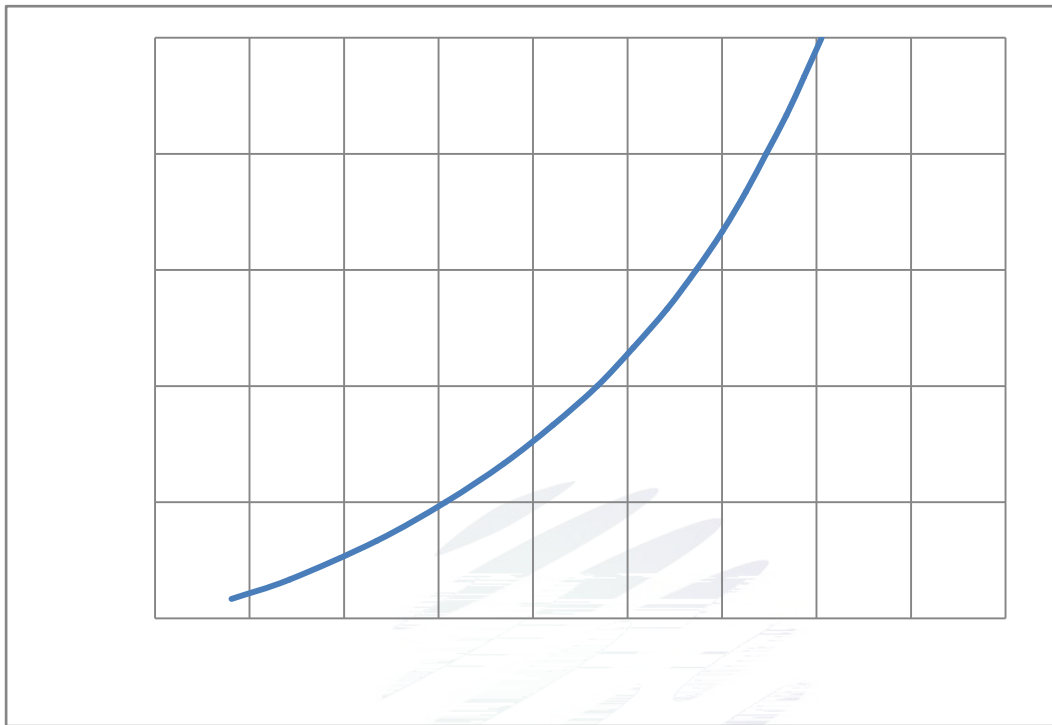


Fig. 1-7 Forward Voltage Vs Forward Current

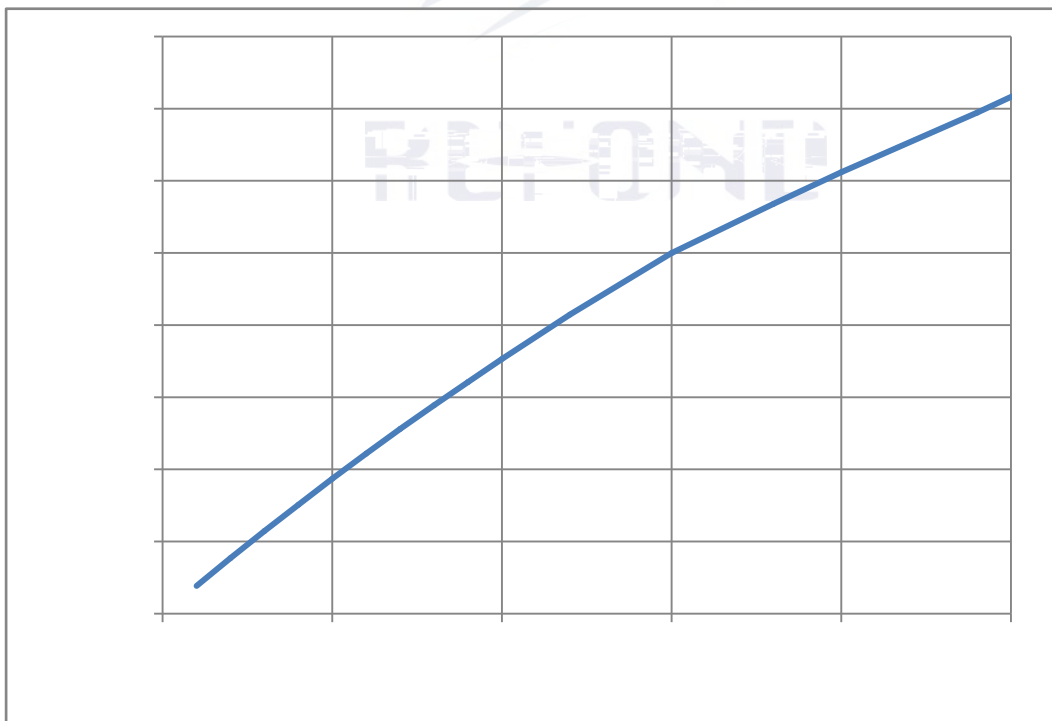


Fig. 1-8 Forward Current Vs Relative Intensity



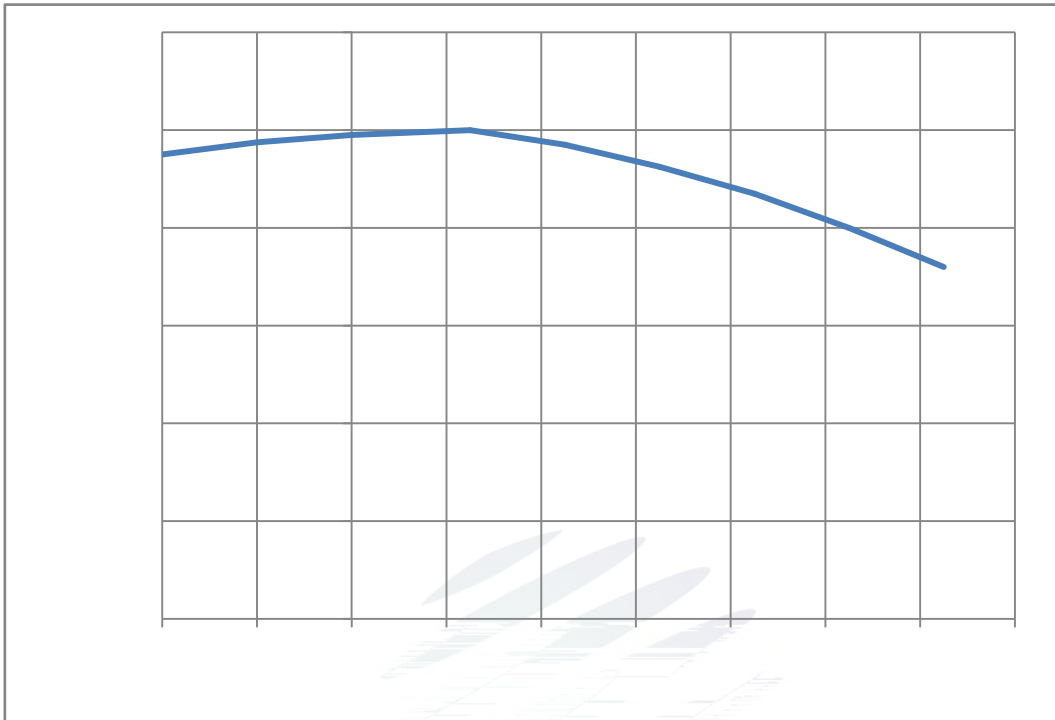


Fig. 1-9 Solder Temperature Vs Relative Intensity

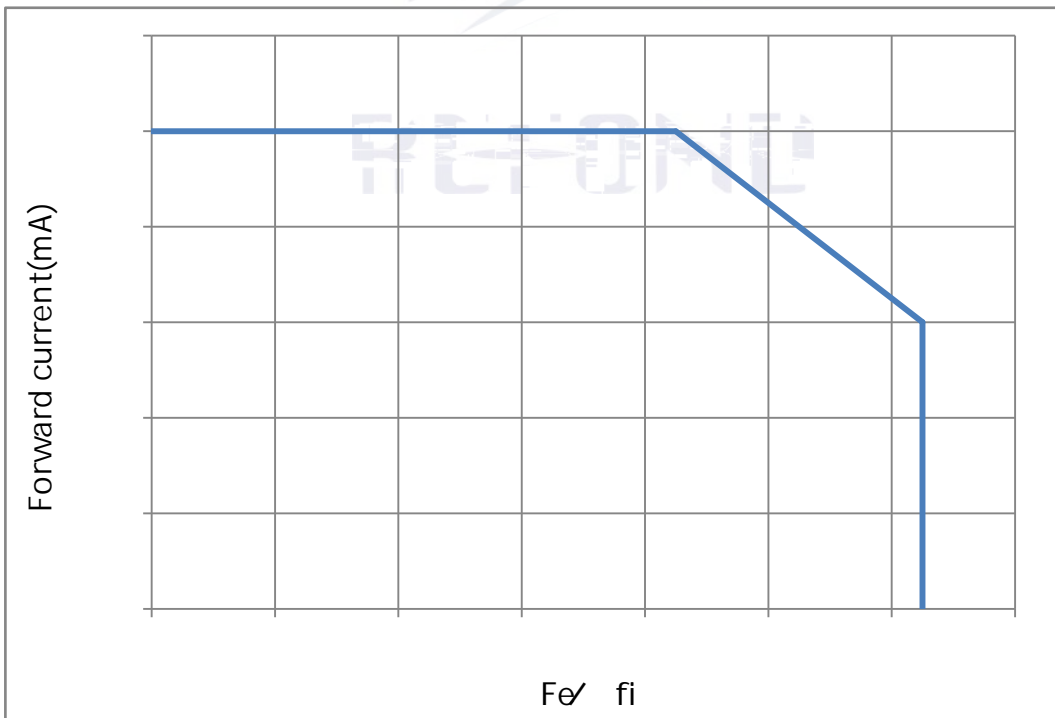


Fig. 1-10 Solder Temperature Vs Forward Current

Tj 150

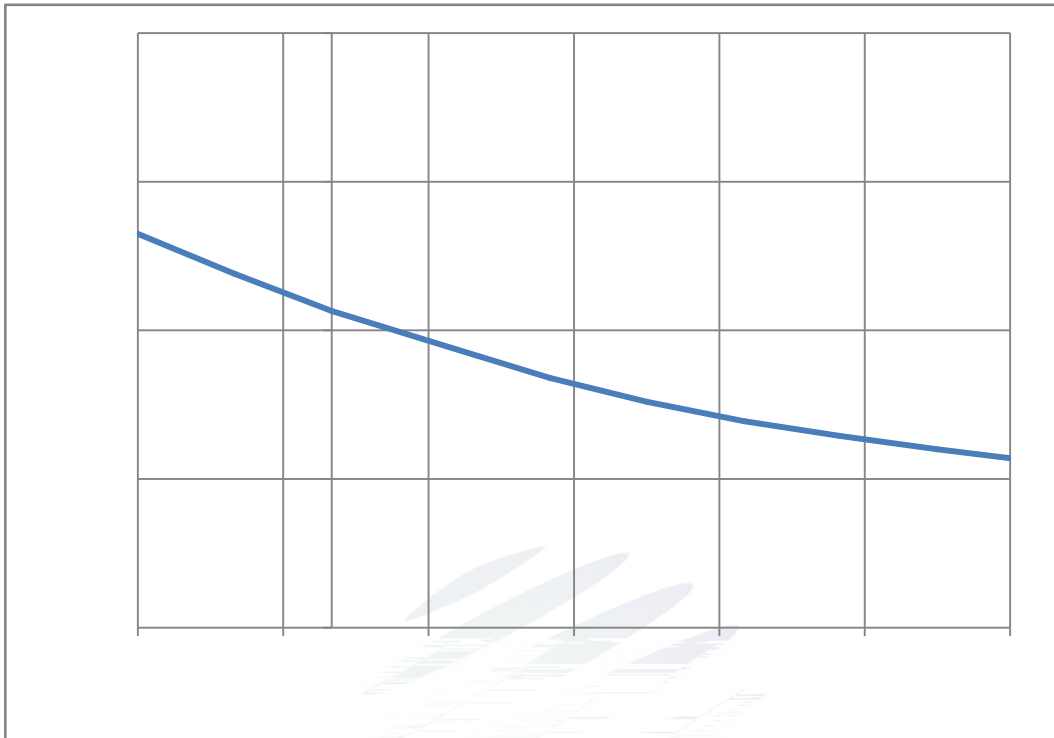


Fig. 1-11 Forward Voltage Vs Solder Temperature

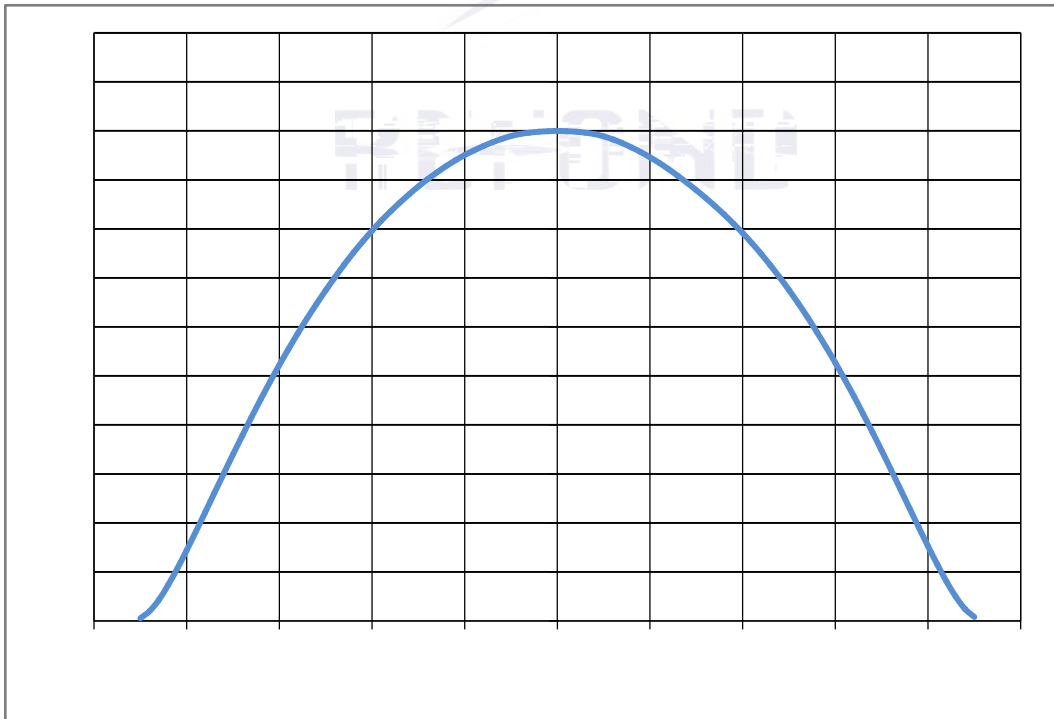


Fig. 1-12 Radiation diagram

Fig. 1-13 Chromaticity Coordinate Vs Solder Temperature

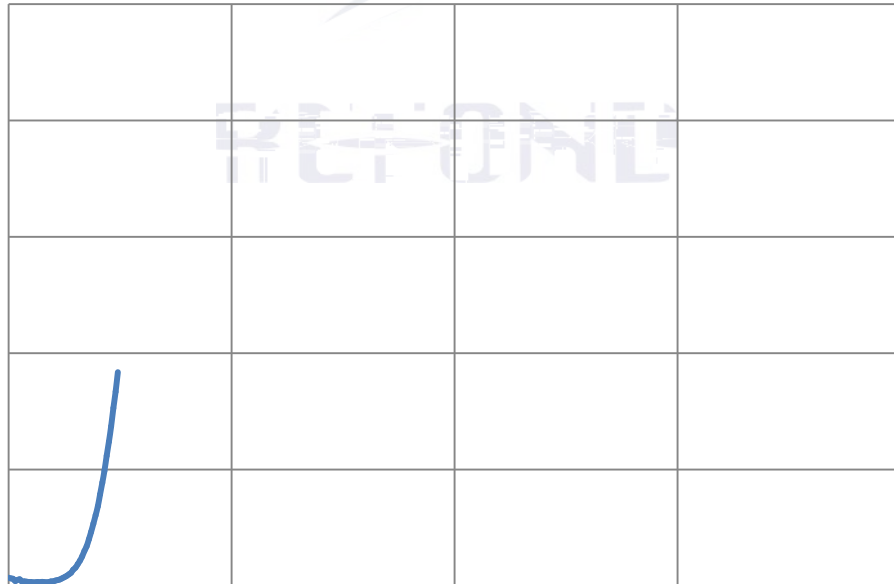


Fig. 1-14 Spectrum Distribution





## 2.4 Reliability Test Items And Conditions

Table 2-3 Reliability Test Items And Conditions

Test Items	Ref.Standard	Test Condition	Time	Quantity	Ac/Re /
Reflow	JESD22-B106	Temp:260 max T=10 sec	2times	20pcs.	0/1
MSL2 2	JESD22-A113	85 / 60%RH	168 hrs.	20pcs.	0/1
Thermal Shock	JEITAED-4701 300307	-40 15min 10s 125 15min	1000 cycle	20pcs.	0/1
Life Test	JESD22-A108	Ta=105 If=150mA	1000hrs.	20pcs.	0/1
High Temperature High Humidity Life Test	JESD22-A101	85 / 85%RH If=150mA	1000hrs.	20pcs.	0/1







## Notes

(1)Reflow soldering should not be done more than twice. If more than 24 hours between the two solderings ,LED will be damaged.

\$&amp; &gt;76

(2)When soldering , do not put stress on the LEDs during heating.

### 3.1.1 Repairing

Repairing should not be done after the LEDs have been soldered. When repairing is unavoidable,a double-head soldering iron should be used (as below figure). It should be confirmed in advance whether the characteristics of LEDs will or not be damaged by repairing.

LED

&gt;76

### 3.1.2 Cautions

(1) The encapsulated material of the LEDs is silicone. Therefore the LEDs have a soft surface on the top of package. The pressure to the top surface will be impacted on the reliability of the LEDs. Precautions should be taken to avoid the strong pressure on the encapsulated part. So when use the picking up nozzle, the pressure on the silicone resin should be proper. LED

&gt;76

(2) Components should not be mounted on warped (non coplanar) portion of PCB. After soldering, do not warp the circuit board.LED

B54

(3) Do not apply mechanical force or excess vibration during the cooling process to normal temperature after soldering. Do not rapidly cool device after soldering.

## 4. Handling Precautions

### 4.1 Handling Precautions

(1) LED operating environment and sulfur element composition cannot be over 100PPM in the LED mating usage material. This is provided for informational purposes only and is not a warranty or endorsement.

>76

# " BB? ž

(2) In order to prevent external material from getting into the inside of LED, which may cause the malfunction of LED, the single content of Bromine element is required to be less than 900PPM, the single content of Chlorine element is required to be less than 900PPM, the total content of Bromine element and Chlorine element in the external materials of the application products is required to be less than 1500PPM. This is provided for informational purposes only and is not a warranty or endorsement.

>76

>76

+ " BB?

+ " BB?

# " BB? ž

(3) VOCs (Volatile organic compounds) emitted from materials used in the construction of fixtures can penetrate silicone encapsulants of LEDs and discolor when exposed to heat and photonic energy. The result can be a significant loss of light output from the fixture. Knowledge of the properties of the materials selected to be used in the construction of fixtures can help prevent these issues. Refond advises against the use of any chemicals or materials that have been found or are suspected to have an adverse affect on device performance or reliability. To verify compatibility, Refond recommends that all chemicals and materials be tested in the specific application and environment for which they are intended to be used. Attaching LEDs, do not use adhesives that outgas organic vapor.

>76

>76

>76

>76

(4) Handle the component along the side surface by using forceps or appropriate tools; Do not directly touch or Handle the silicone lens surface, it may damage the internal circuitry.



Table 4-1 Storage

Conditions		Temperature	Humidity	Time
Storage	Before Opening Aluminum Bag	30	75%	Within 1 Year From Date
	After Opening Aluminum Bag	30	60%	Recommended for use within 24 hours 24
Baking		60 ± 5	-	24hours 24

(8) If the moisture absorbent material silica gel has faded away or the LEDs have exceeded the storage time, baking treatment should be performed after unpacking and based on the following condition 60 ± 5 for above 24 hours.

( " f ' \$ &

If the package is flatulence or damaged, please notify the sales staff to assist.

(9) Similar to most Solid state devices; LEDs are sensitive to Electro-Static Discharge (ESD) and Electrical Over Stress (EOS). >76

(10) Other points for attention, please refer to our relevant information.

Date	Revisor	Version	Verifier	Remarks
2023/10/25	Xian Zhou	E0	Zhu Yiming	New issue



REFOND

Declare

This specification is written both in English and in Chinese and the latter is formal.